



Full Material Declaration for attached parts list

Report generated: 16 October 2024, 10:05 GMT



Diotec Semiconductor AG
DUNS number: 330866844
-, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany
Declarations authorised by
Udo Steinebrunner, Product Manager, -

Declaration effective from: 02 January 2014 [Approved: 16 October 2024 10:04 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.65%	Silicon	7440-21-3	100%
			Oxirane, [[4-(1,1-dimethylethyl)phenoxy]methyl]-	3101-60-8	4%
Die attach	Other nonferrous metals	0.29%	Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	16%
			Silver	7440-22-4	80%
			Carbon black	1333-86-4	1%
			phenolic epoxy resin	61788-97-4	1.5%
			Silicon Dioxide	7631-86-9	5%
Encapsulation	EP (Epoxy resin)	59.55%	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	7.5%
			Fused quartz	60676-86-0	85%
			COPPER, ELEMENTAL	7440-50-8	100%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	4.42%	Tin elemental	7440-31-5	100%
Leadfinish	Tin plating	2.27%	Tin elemental	7440-31-5	1.5%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	32.82%	COPPER, ELEMENTAL	7440-50-8	98.5%

Attached parts list

Part number	Part name
SOT-23 PbF & HF Ag	Diode / Transistor SMD